

Ceramic Chip-on-Board Mixer Quads



DME, DMF, DMJ Series

Features

- For Microwave MIC Assembly & Automated High Volume Manufacturing Lines
- Mechanically Rugged Design
- Three Barrier Heights for Optimized Mixer Performance
- Wide Range of Capacitances Available
- Automated Assembly Methods
- Virtually Any LO Requirement Can Be Met With Choice Of Barrier Height
- Low Conversion Loss Mixers Can Be Designed Using Standard "N" Type Material
- 100% DC Tested



Octo Quad Ring
Chip-on-Board



S-Band Crossover Ring Quad
Chip-on-Board

Maximum Ratings

Tstg:	-65°/+175°C
Top:	-65°/+150°C
Pdiss CW:	75 mW/junction
I max:	50 mA
PIV:	2.0 – 3.0V at 10 μ A

Description

The Ceramic Chip-on-Board (COB) Mixer Quads are designed for a high degree of device reliability and ease of use in both commercial and industrial

applications. They are designed to offer the utmost in performance while achieving price targets for cost sensitive commercial systems.

Electrical Specifications

Part Number	Drive Level	V _F I _F = 1 mA (mV)		V _F I _F = 5 mA (mV)		V _F I _F = 10 mA (mV)		(B) V _F ¹ I _F = 10 mA (mV)	C _{TL} V _R = 0V, f = 1 MHz (pF)	(B) C _{TL} ¹ V _R = 0V, f = 1 MHz (pF)	R _T I _F = 10 mA (Ohms)	Outline Drawing Number
		min	max	min	max	min	max	min	max	max	max	
Ring Quad												
DMF3487	Low	220	290	—	—	—	—	10	0.55	0.07	8	543–002
DME3486	Medium	300	400	—	—	390	470	15	0.55	0.07	8	543–002
DMJ3476	High	525	625	—	—	600	700	15	0.55	0.07	8	543–002
Crossover Ring Quad												
DMF3591	Low	220	290	260	330	—	—	10	0.55	0.07	8	543–010
DME3592	Medium	300	400	—	—	390	470	15	0.55	0.07	8	543–010
DMJ3593	High	525	625	—	—	600	700	15	0.55	0.07	8	543–010
Back-to-Back Crossover Quad ²												
DMF3484	Low	220	290	260	330	—	—	15	0.55	0.07	8	545–065
DME3479	Medium	300	400	—	—	360	480	15	0.55	0.07	8	545–065
DMJ3485	High	525	625	—	—	600	700	20	0.55	0.07	8	545–065

1. Balance all junctions.

2. Parameters are for single leg of diode.

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